3.65x6.15mm SINGLE CHIP LED LIGHT BAR

Part Number: WP1043SRD

Super Bright Red

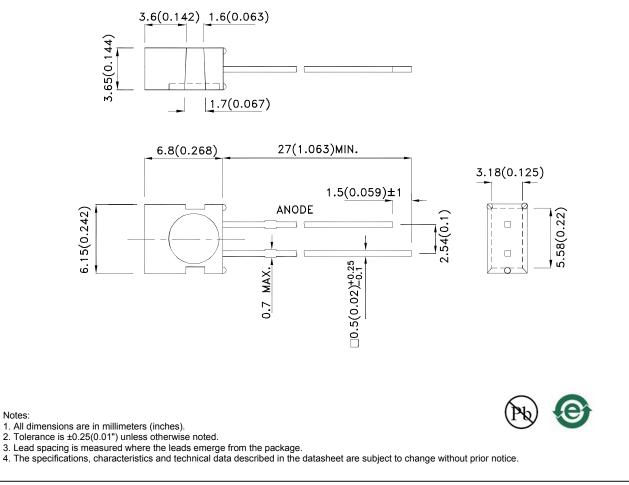
Features

- Flat rectangular light emitting surface.
- Single color.
- Ideal as flush mounted panel indicators.
- Excellent on/off contrast.
- Long life solid state reliability.
- This series are tin-dipped.
- RoHS compliant.

Description

The Super Bright Red source color devices are made with Gallium Aluminum Arsenide Red Light Emitting Diode.

Package Dimensions



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Salaction Guida

Selection Guide										
Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]					
			Min.	Тур.	201/2					
WP1043SRD	Super Bright Red (GaAlAs)	Red Diffused	40	100	100°					
			*20	*50						

Notes:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity/ luminous Flux: +/-15%.

*Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions	
λpeak	Peak Wavelength	Super Bright Red	655		nm	I⊧=20mA	
λD [1]	Dominant Wavelength	Super Bright Red	640		nm	I⊧=20mA	
Δλ1/2	Spectral Line Half-width	Super Bright Red	20		nm	I⊧=20mA	
С	Capacitance	Super Bright Red	45		pF	VF=0V;f=1MHz	
Vf [2]	Forward Voltage	Super Bright Red	1.85	2.5	V	I⊧=20mA	
IR	Reverse Current	Super Bright Red		10	uA	VR = 5V	

Notes:

1.Wavelength: +/-1nm.

2. Forward Voltage: +/-0.1V. 3.Wavelength value is traceable to the CIE127-2007 compliant national standards.

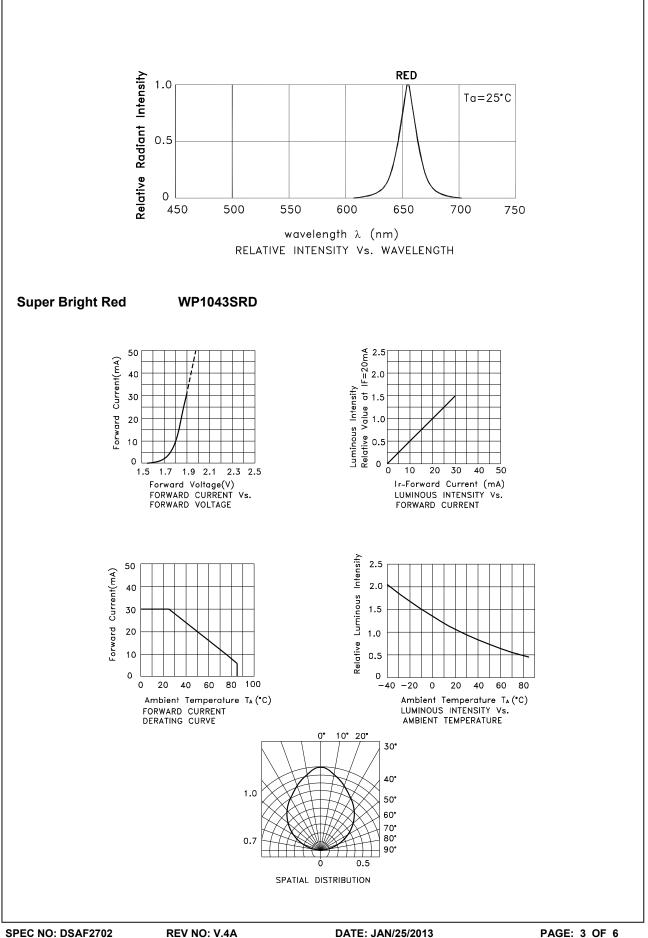
Absolute Maximum Ratings at TA=25°C Parameter Super Bright Red Units Power dissipation 75 mW DC Forward Current 30 mΑ Peak Forward Current [1] 155 mΑ 5 V Reverse Voltage Operating/Storage Temperature -40°C To +85°C Lead Solder Temperature [2] 260°C For 3 Seconds Lead Solder Temperature [3] 260°C For 5 Seconds

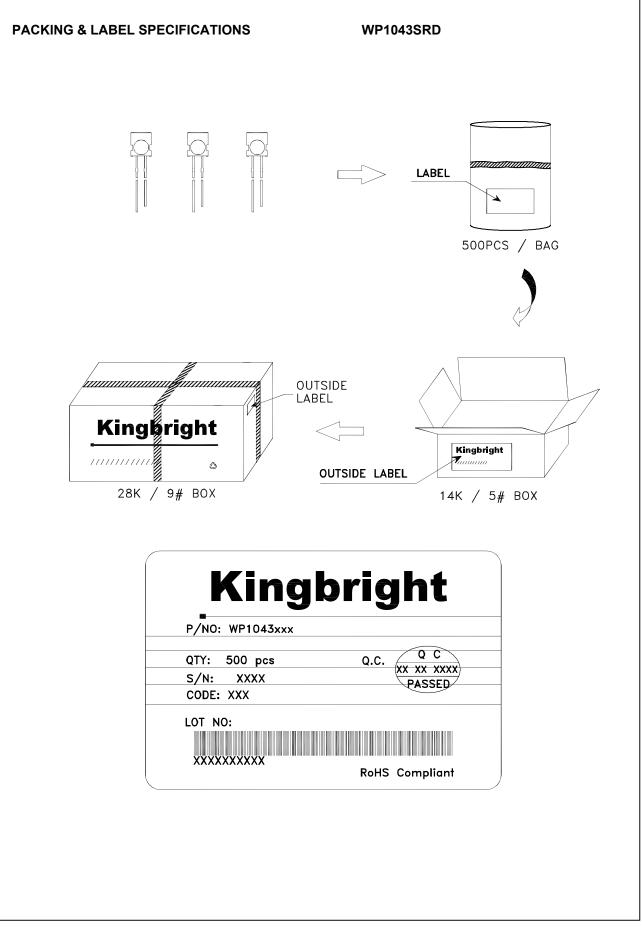
Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

2. 2mm below package base.

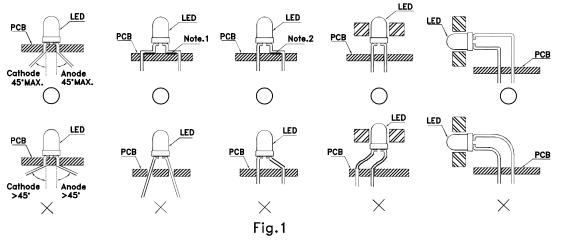
3. 5mm below package base.





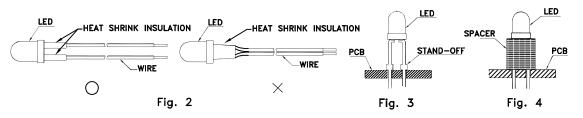
PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)

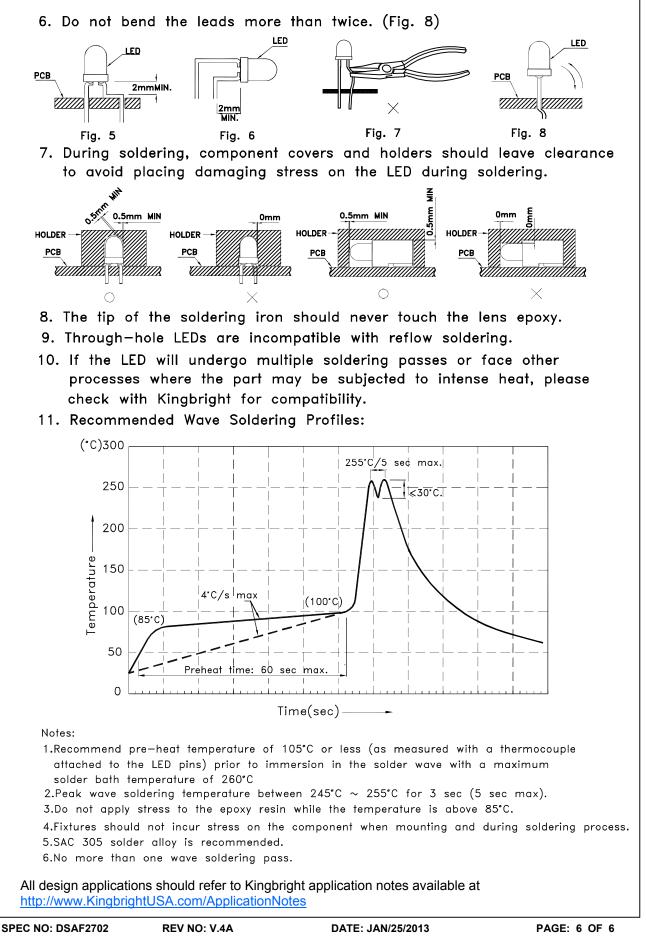


" \bigcirc " Correct mounting method "imes" Incorrect mounting method

- 2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit. (Fig.2)
- 3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.



- 4. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)
- 5. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)



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